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SEMICONDUCTOR

**AO4306**

**30V N-Channel MOSFET**

### General Description

The AO4306 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for high side switch in SMPS and general purpose applications.

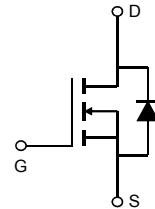
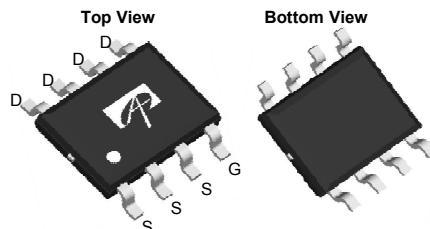
### Product Summary

$V_{DS}$	30V
$I_D$ (at $V_{GS}=10V$ )	13A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	< 11.5mΩ
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$ )	< 15.5mΩ

100% UIS Tested  
100%  $R_g$  Tested



SOIC-8



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>A</sup>	$I_D$	13	A
Current $T_A=70^\circ C$		10.4	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	100	
Avalanche Current <sup>C</sup>	$I_{AS}$	22	A
Avalanche energy $L=0.1mH$ <sup>C</sup>	$E_{AS}$	24	mJ
Power Dissipation <sup>B</sup>	$P_D$	3.1	W
$T_A=70^\circ C$		2	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup> $t \leq 10s$	$R_{\theta JA}$	31	40	°C/W
Maximum Junction-to-Ambient <sup>A,D</sup> Steady-State		59	75	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	16	24	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$			$\pm100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.5	1.9	2.5	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	100			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=12\text{A}$		9.5	11.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$ $T_J=125^\circ\text{C}$		14	17	
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=12\text{A}$		45		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.75	1	V
$I_S$	Maximum Body-Diode Continuous Current				4	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		760		pF
$C_{\text{oss}}$	Output Capacitance			125		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			70		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	0.8	1.6	2.4	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=12\text{A}$		14	25	nC
$Q_g(4.5\text{V})$	Total Gate Charge			6.6	12	nC
$Q_{\text{gs}}$	Gate Source Charge			2.4		nC
$Q_{\text{gd}}$	Gate Drain Charge			3		nC
$Q_{\text{gs}}$	Gate Source Charge	$V_{GS}=4.5\text{V}, V_{DS}=15\text{V}, I_D=12\text{A}$		2.4		nC
$Q_{\text{gd}}$	Gate Drain Charge			3		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=1.25\Omega, R_{\text{GEN}}=3\Omega$		4.4		ns
$t_r$	Turn-On Rise Time			9		ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			17		ns
$t_f$	Turn-Off Fall Time			6		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=12\text{A}, dI/dt=500\text{A}/\mu\text{s}$		7		ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=12\text{A}, dI/dt=500\text{A}/\mu\text{s}$		8		nC

A. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using  $\leqslant 10\text{s}$  junction-to-ambient thermal resistance.

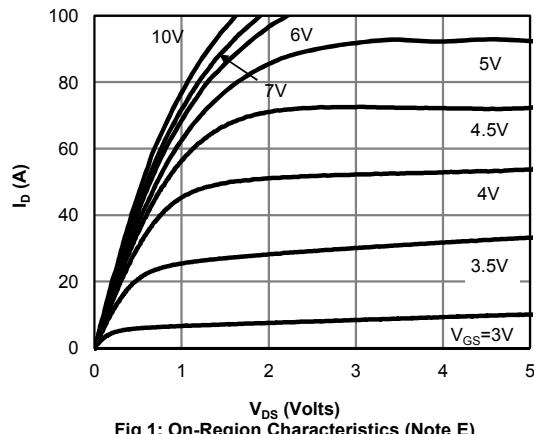
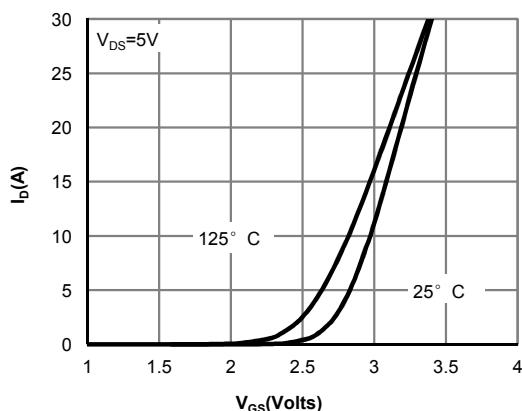
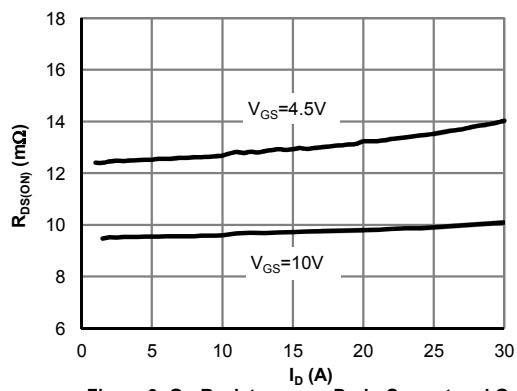
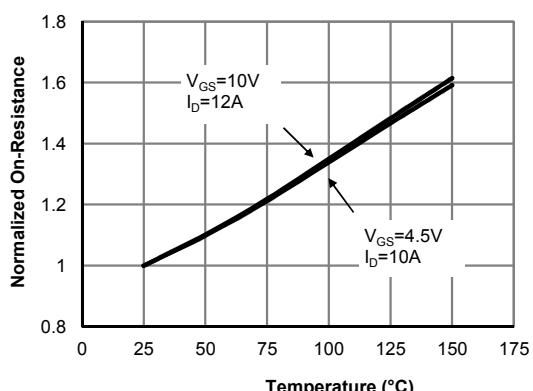
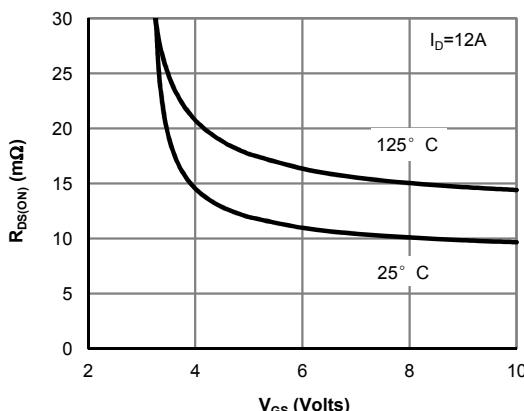
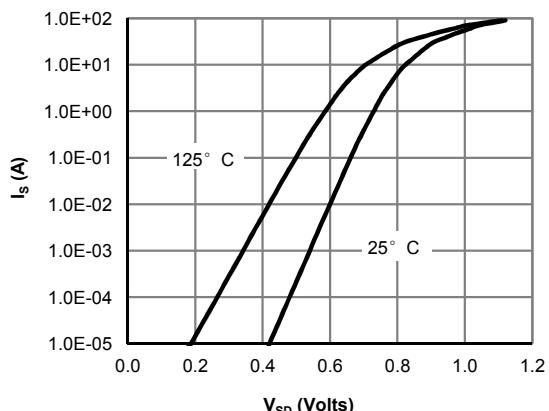
C. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

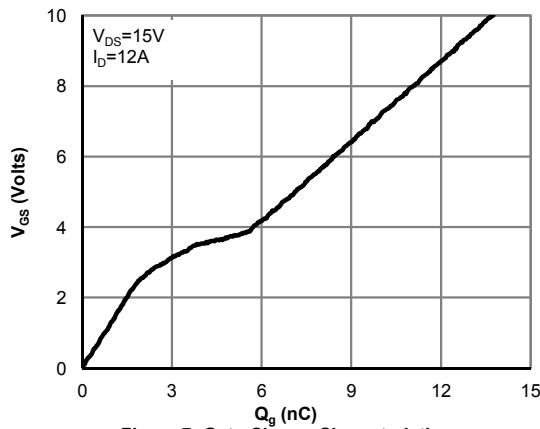
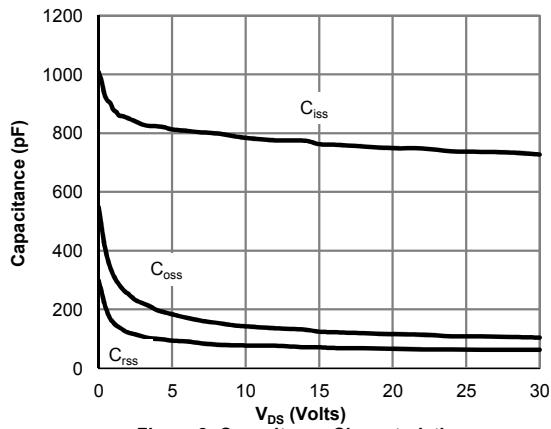
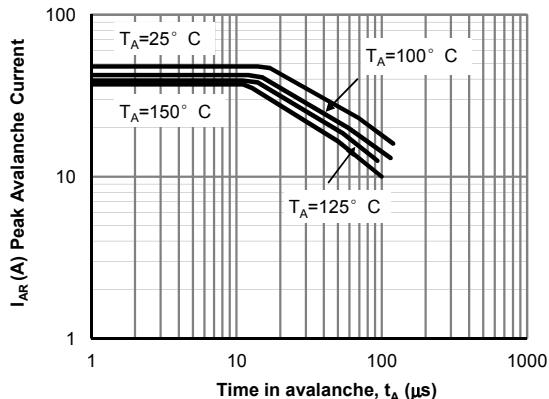
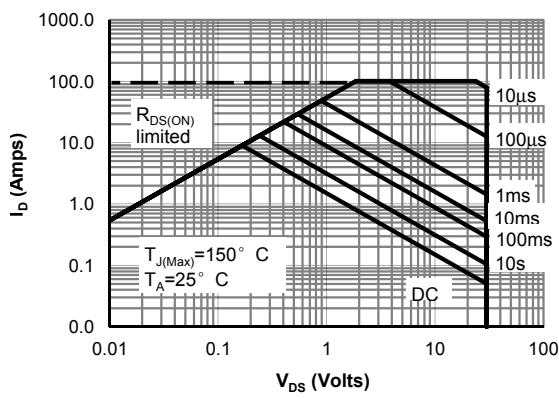
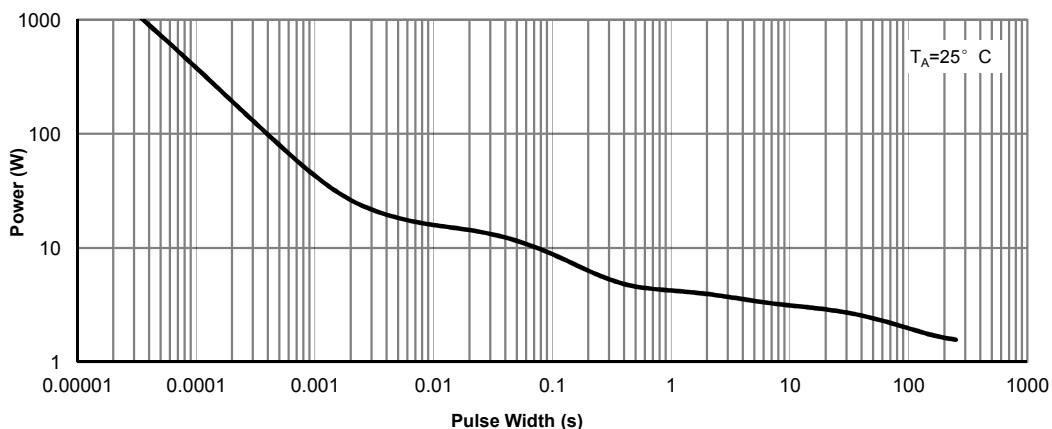
D. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using  $<300\mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

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**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Fig 1: On-Region Characteristics (Note E)**

**Figure 2: Transfer Characteristics (Note E)**

**Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)**

**Figure 4: On-Resistance vs. Junction Temperature (Note E)**

**Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)**

**Figure 6: Body-Diode Characteristics (Note E)**

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 7: Gate-Charge Characteristics**

**Figure 8: Capacitance Characteristics**

**Figure 9: Single Pulse Avalanche capability (Note C)**

**Figure 10: Maximum Forward Biased Safe Operating Area (Note F)**

**Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)**

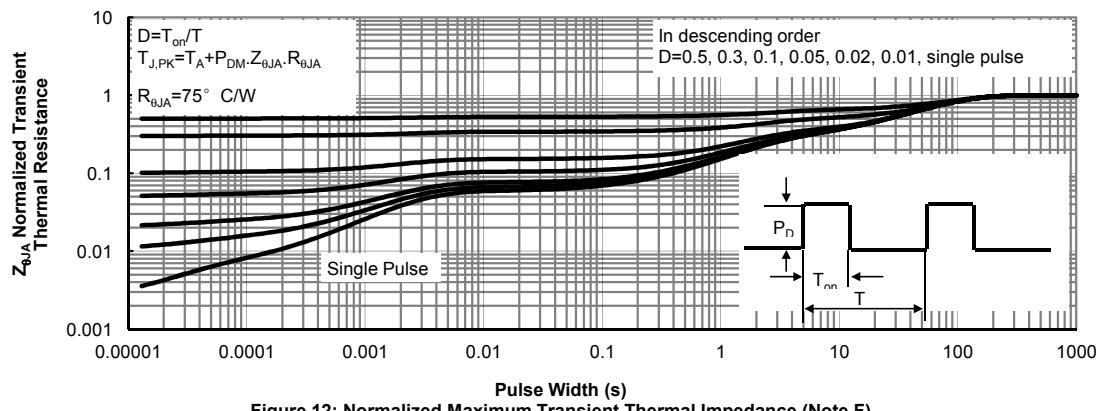
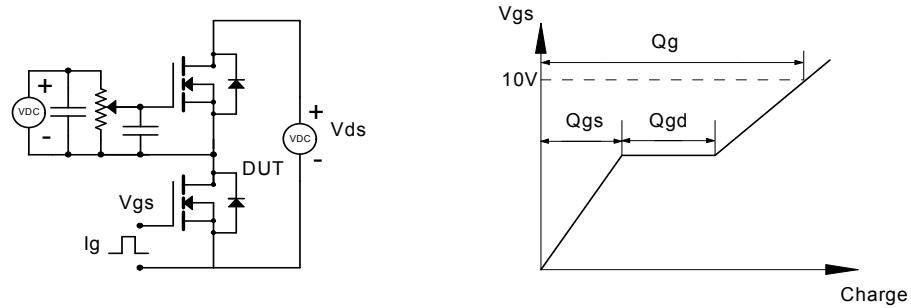
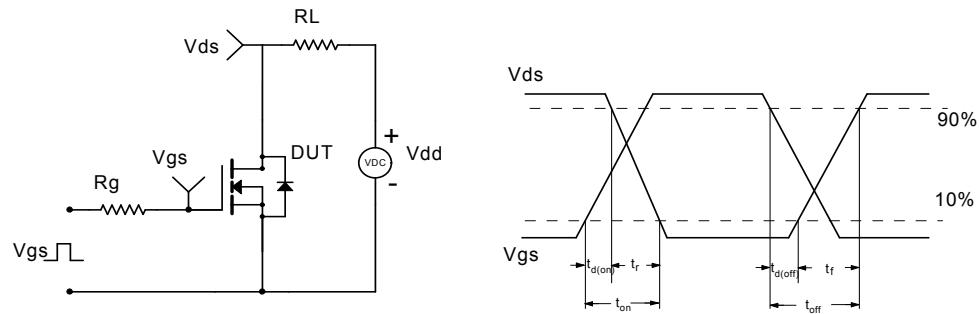
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

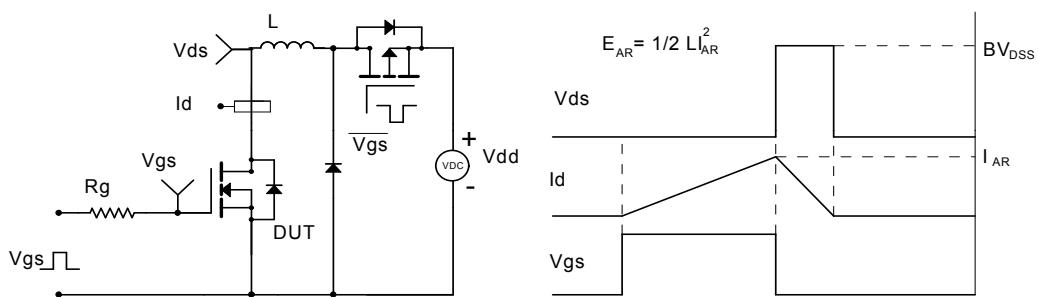
### Gate Charge Test Circuit & Waveform



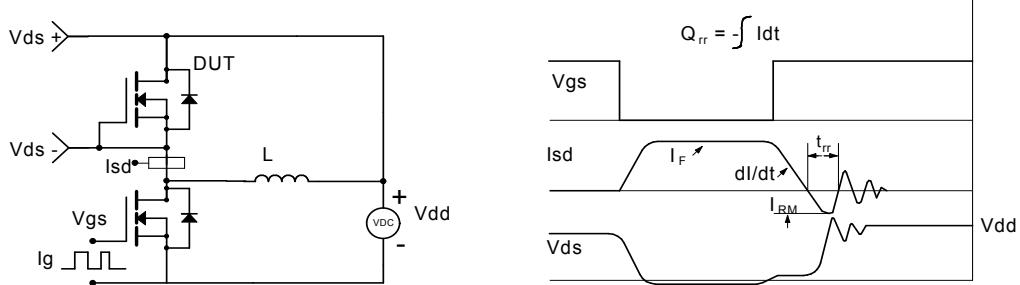
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



### Diode Recovery Test Circuit & Waveforms



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